



Product Content Sheet

Package family	QFN	
Date	2005-02-28	
Version	RoHS	

Composition part	Material group	Materials	CAS if applicable	Average mass [weight-% *)	Sum [%]	Traces	
Chip	Silicon and inorganic compounds	Silicon	7440-21-3	100	4.63		
Wires	Nobel Metal	Gold	7440-57-5	99.99	0.50		
Leadframe	Alloy	Cu	7440-50-8	97.50	42.12		
		Fe	7439-89-6	2.35	0.995		
		P	7723-14-0	0.03	0.012		
		Zn	7440-66-6	0.12	0.050		
Diepad	Aluminised Die		N/A	N/A	N/A		
Mold compound	Silica	SiO2	60676-86-0	89	45.18		
		Epoxy resin	Biphenyl	Confidential	10.8	5.49	
			Carbon Black	1333-86-4	0.2	0.10	
DA Epoxy	Epoxy	Epoxy resin	Confidential	23	0.147		
			Silver	7440-02-24	77	0.492	
Leadfinish	Metal Alloy	Tin	7440-31-5	100	0.3		
Marking	Laser			0	0		
Sum in total:					100		

Weight range	0.13 gram
Fluctuation margin	+/-25%

or:

Case sizes**) and weight range

--

*) related to package weight; weight in particular, see corresponding *package weight list*

**) optional

Not part of package family	
----------------------------	--

Company	Chipcon	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight. Higher limits are accepted if the substance or material is legally regulated (see note no. 2). 2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address: http://www.eicta.org/Content/Default.asp?PageID=113 . 3) Substances, materials etc. with possible harmful effects on
Address	Gaustadalleen 21, 0349 Oslo, Norway	
E-mail	support@chipcon.com	
Internet	www.chipcon.com	

- 4) human beings and the environment are listed.
 There are no risks for human beings and to the environment if products are properly used as designated.
 This shall not apply to risks caused during procedures for disposal etc.
- 5) All statements herein are based on our present knowledge.
 If our products are used properly, there are no risks to human beings and/or the environment.



Package Weight List

(Single weights of Products, materials data see Product Content Sheet on previous page)

Package family	QFN
Date	2005-02-28
Version	

Uspec short*)	Package family*)	Package	Internal package code	Pin count	Weight [grams]	Remark
10273-001	QFN	QFN32	QFN32	32	0.13 g	Device: CC1020

*) USpec short name and Package family are optional, e.g. for summary of several package weight lists

Company	Chipcon
Address	Gaustadalleen 21, 0349 Oslo, Norway
E-mail	support@chipcon.com
Internet	www.chipcon.com

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
Low Power Wireless	www.ti.com/lpw	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2007, Texas Instruments Incorporated